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Set-Bond 839

Set-Bond 839 is a 100% solids epoxy system. It is a filled, thixotropic paste compound with adjustable Flexibility offering good mechanical bond, peel strength and thermal shock resistance. It also has good adhesion to glass, ceramics, most metals and plastics. It can be cured at room temperature or at elevated temperatures.

Properties-Uncured:	Part A	Part B
Color, Visual	White	Amber/Neutral
Mixed Viscosity, cps	Paste	
Specific Gravity	1.15	
Mix Ratio, by weight	1 to 1 RIGID 1 to 2 SEMI- RIGID 1 to 3 FLEXIBLE	
Pot Life @25 ºC	45 to 60 mins	
Shelf Life @25 ºC	6 months	

Physical Properties-Cured:	
Durometer (Shore D)	45-80 varies with ratio
Flexural Strength, psi	5,800
Tensile Strength, psi	5,500
Tensile Elongation, %	2-10
Lap Shear Strength, psi	3000
Service Temperature ºC	105

Electrical:	
Dielectric Strength, volts/Mil	405
Dielectric Constant, 60hz	3
Dissipation Factor, 60hz	0.002
Volume Resistivity, ohm-cm	1×10^{14}
Thermal Conductivity, btu-in/(ft^2)(hr)(ºF)	1.6

Mixing Instruction:

1. Pre-mix both components in their original containers to insure consistency.
2. Measure out equal parts (by weight) of both components.
3. Mix thoroughly, scraping the sides and bottom of container
4. Evacuate @29in. Hg for void-free casting.
5. Pour into unit or cavity.

Cure Schedule: 16 to 24 hours at Room Temperature, 4-6 hours at 55 ºC, 30 minutes at 80 ºC, or 15 minutes at 105 ºC. Note ultimate properties attained after 4-6 days at room temperature (25 ºC)

Warranty

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